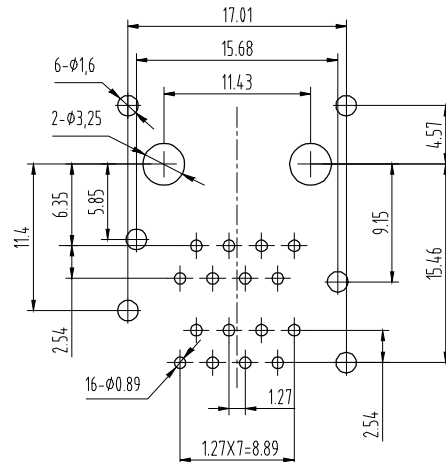
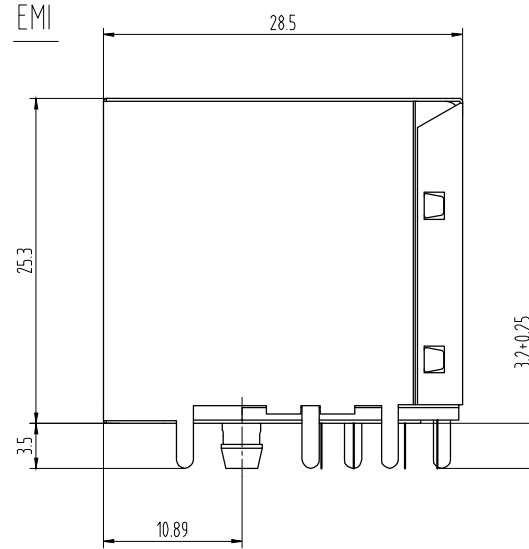
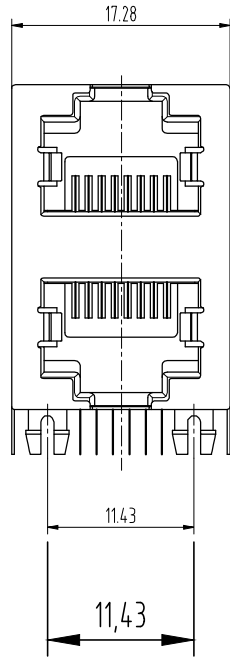


REV	ECO	DESCRIPTION	DRFT	CHKD



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE $\phi 0.45\text{mm}$.
- 3.PLATING :GOLD PLATING $\text{Fu} \sim 50\text{u}''$ OVER NICKEL.
- 4.SHIELD :0.20mm THICKNESS COPPER ALLOY WITH NICKEL PLATED.

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :30 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40°C~+85°C
2. OPERATION : 0°C TO 70°C.

PART NUMBER:

		ZP59B	8	X	-	X	X	X	X			
	59 2xN JACK											
POSITIONS	CONTACTS	PORTS	SHIELD	BACK PEG	PLASTIC	LOGO	GOLD PLATING					
6-6 POSITIONS	2-2 CONTACTS	1-2X1	0-W/O SHIELD	0-W/O BACK PEG	1-PBT	0-W/O LOGO	0-Fu*					
8-8 POSITIONS	4-4 CONTACTS	2-2X2	1-SHIELD W/ EMI	1-1 BACK PEG	2-NYLON66	1-W/ ZPY	1-15u*					
0-10 POSITIONS	6-6 CONTACTS	4-2X4	2-SHIELD W/O EMI	2-2 BACK PEG	3-NYLON46	2-W/ UL	2-3u*					
	8-8 CONTACTS	5-2X5	3-W/ BACK EMI	3-3 BACK PEG		3-W/ ZPY&UL	3-6u*					
	1-10 CONTACTS	6-2X6	4-HALF SHIELDED				4-15u*					
		8-2X8					5-30u*					
							6-50u*					

TOLERANCES EXCEPT AS NOTED	MM (INCH)	DFTO: SHB	DATE: 2007.05.03	深圳市富港科技有限公司		
		CHKD: LANBO	DATE: 2007.05.03			
		MFO:	DATE:	RJ-059B-2X1-4		
		APPVL:	DATE:			
		MATERIAL :				
REFINED LISTS	MM	QTY :		DRAWING NO.	SIZE	REV
	.0 ± 0.15			/PART NO.	A3	0
	.00 ± 0.075					
	.000 ± 0.05					
ANGLES ± 0.5						
THIRD ANGLE PROJECTION		SCALE :		DO NOT SCALE DRAWING	SHEET X	OF Y